

Title (en)

Method and device for sealing of a thin film electroluminescent device

Title (de)

Verfahren und Vorrichtung zum Abdichten einer Dünnschicht-Elektrolumineszenzanordnung

Title (fr)

Procédé et dispositif pour l'étanchement d'un dispositif électroluminescent à couche mince

Publication

EP 0751699 A2 19970102 (EN)

Application

EP 96304544 A 19960619

Priority

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Abstract (en)

A method of forming a seal for a thin film electroluminescent device (10) includes using deposition techniques (36) to form an integral thin film encapsulating layer (26; 28). Plasma enhanced chemical vapor deposition is utilized, allowing the formation of the seal to take place at substantially room temperature. A pre-bake (34) is performed at an elevated temperature in an evacuated environment prior to the formation of the thin film encapsulating layer. A silicon nitride film may be used as a single-film encapsulating layer, or may be used with another material (30) in the fabrication of a multi-film encapsulating layer.

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